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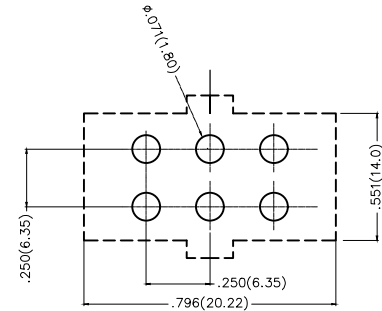
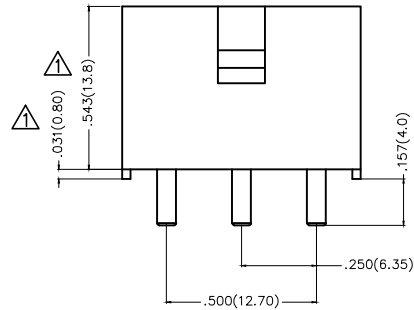
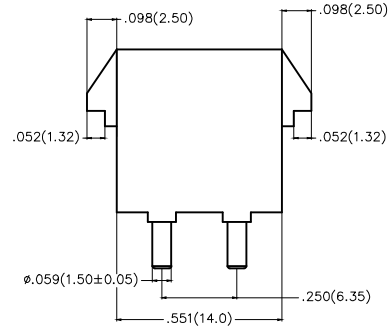
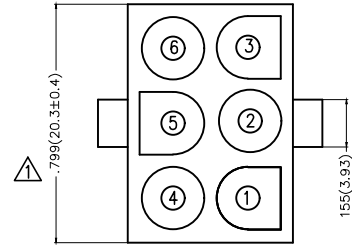
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	Size change	11/OCT/22	MATT	CHERRY
2	△	Flammability Change	02/AUG/23	MATT	LEO

Electrical

Current Rating: 13A AC(rms)/DC  
 Voltage Rating: 300V AC(rms)/DC  
 Contact Resistance: 20 mΩ Max  
 Insulation Resistance: 1000 MΩ MIN  
 Withstanding Voltage: 1500V AC r.m.s  
 Temperature Range-Operating: -25°C~+85°C

Material and Plating

Housing: PA66( UL 94V-2) △  
 Contact Pin: Brass  
 Plating: Tin Plated



Recommended P.C.Board Layout

<p>THIRD ANGLE PROJECTION</p>	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF63502-D06S22TB	ITEM NO. FWF63502	<p>Leader Of Industry</p>
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20)	X'±5" .X'±2"	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 6.35mm 180° Vertical (DIP)	
SCALE 5:1	SIZE A4	X.XX±.006(0.15) X.XXX±.004(0.10)	DRAWN BY CHERRY	DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		REV 2 SHEET NO. 1/1

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